FAIRCHILD SEMICONDUCTOR TM

JANSR2N7298
Formerly FRF450R4

Data Sheet | **November 1998** | **File Number 4290**

Radiation Hardened, N-Channel Power MOSFET

The Intersil has designed a series of SECOND GENERATION hardened power MOSFETs of both N-Channel and P-Channel enhancement types with ratings from 100V to 500V, 1A to 60A, and on resistance as low as 25mΩ. Total dose hardness is offered at 100K RAD (Si) and 1000K RAD (Si) with neutron hardness ranging from 1E13 for 500V product to 1E14 for 100V product. Dose rate hardness (GAMMA DOT) exists for rates to 1E9 without current limiting and 2E12 with current limiting.

This MOSFET is an enhancement-mode silicon-gate power field effect transistor of the vertical DMOS (VDMOS) structure. It is specially designed and processed to exhibit minimal characteristic changes to total dose (GAMMA) and neutron (n^o) exposures. Design and processing efforts are also directed to enhance survival to dose rate (GAMMA DOT) exposure.

Also available at other radiation and screening levels. See us on the web, Intersil's home page: http://www.intersil.com. Contact your local Intersil Sales Office for additional information.

Ordering Information

PART NUMBER	PACKAGE	BRAND
JANSR2N7298	TO-254AA	JANSR2N7298

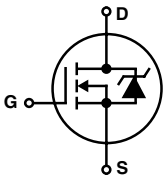
Die family TA17655.

MIL-PRF-19500/605.

Features

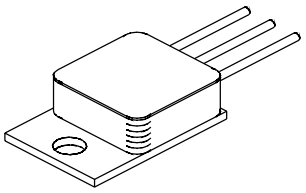
- 9A, 500V, $r_{DS(ON)}$ = 0.615Ω
- Total Dose
  - Meets Pre-RAD Specifications to 100K RAD (Si)
- Dose Rate
  - Typically Survives 3E9 RAD (Si)/s at 80% BV_{DSS}
  - Typically Survives 2E12 if Current Limited to I_{DM}
- Photo Current
  - 30nA Per-RAD(Si)/s Typically
- Neutron
  - Maintain Pre-RAD Specifications . . . . . for 3E12 Neutrons/cm^2
  - Usable to 3E13 Neutrons/cm^2

Symbol



Package

TO-254AA



CAUTION: Beryllia Warning per MIL-S-19500 refer to package specifications.

Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

		JANSR2N7298	UNITS
Drain to Source Voltage	V_{DS}	500	V
Drain to Gate Voltage (R_{GS} = 20kΩ)	V_{DGR}	500	V
Continuous Drain Current			
$T_C = 25^oC$	I_D	9	A
$T_C = 100^oC$	I_D	6	A
Pulsed Drain Current	I_{DM}	27	A
Gate to Source Voltage	V_{GS}	±20	V
Maximum Power Dissipation			
$T_C = 25^oC$	P_T	125	W
$T_C = 100^oC$	P_T	50	W
Derated Above 25^oC		1.00	$W/^oC$
Single Pulsed Avalanche Current, L = 100μH, (See Test Figure)	I_{AS}	27	A
Continuous Source Current (Body Diode)	I_S	9	A
Pulsed Source Current (Body Diode)	I_{SM}	27	A
Operating and Storage Temperature	T_{JC}, T_{STG}	-55 to 150	^oC
Lead Temperature (During Soldering) (Distance >0.063in (1.6mm) from Case, 10s Max)	T_L	300	^oC
Weight (Typical)		9.3	g

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	I_D = 1mA, V_{GS} = 0V		500	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, I_D = 1mA	$T_C = -55^oC$	-	-	5.0	V
			$T_C = 25^oC$	2.0	-	4.0	V
			$T_C = 125^oC$	1.0	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 400V, V_{GS} = 0V	$T_C = 25^oC$	-	-	25	μA
			$T_C = 125^oC$	-	-	250	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±20V	$T_C = 25^oC$	-	-	100	nA
			$T_C = 125^oC$			200	nA
Drain to Source On-State Voltage	$V_{DS(ON)}$	V_{GS} = 10V, I_D = 9A				5.81	V
On Resistance	$r_{DS(ON)}$	I_D = 6A, V_{GS} = 10V	$T_C = 25^oC$	-	-	0.615	Ω
			$T_C = 125^oC$	-	-	1.60	Ω
Turn-On Delay Time	$t_{d(ON)}$	V_{DD} = 250V, I_D = 9A, R_L = 27.8Ω, V_{GS} = 10V, R_{GS} = 25Ω		-	-	148	ns
Rise Time	t_r			-	-	196	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	-	800	ns
Fall Time	t_f			-	-	180	ns
Total Gate Charge	$Q_{g(TOT)}$	V_{GS} = 0V to 20V	V_{DD} = 250V, I_D = 5A, R_L = 27.8Ω	-	-	486	nC
Gate Charge at 10V	$Q_{g(10)}$	V_{GS} = 0V to 10V		-	-	264	nC
Threshold Gate Charge	$Q_{g(TH)}$	V_{GS} = 0V to 2V		-	-	16	nC
Gate Charge Source	Q_{gs}			-	-	56	nC
Gate Charge Drain	Q_{gd}			-	-	126	nC
Thermal Resistance Junction to Case	$R_{\theta JC}$			-	-	1.0	$^oC/W$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$			-	-	48	$^oC/W$

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Forward Voltage	V_{SD}	I_{SD} = 9A	0.6	-	1.8	V
Reverse Recovery Time	t_{rr}	I_{SD} = 9A, dI_{SD}/dt = 100A/μs	-	-	3000	ns

Electrical Specifications up to 100K RAD $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
Drain to Source Breakdown Volts	(Note 3)	BV_{DSS}	V_{GS} = 0, I_D = 1mA	500	-	V
Gate to Source Threshold Volts	(Note 3)	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 1mA	2.0	4.0	V
Gate to Body Leakage	(Notes 2, 3)	I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	100	nA
Zero-Gate Leakage	(Note 3)	I_{DSS}	V_{GS} = 0, V_{DS} = 400V	-	25	µA
Drain to Source On-State Volts	(Notes 1, 3)	$V_{DS(ON)}$	V_{GS} = 10V, I_D = 9A	-	5.81	V
Drain to Source On Resistance	(Notes 1, 3)	$r_{DS(ON)}$	V_{GS} = 10V, I_D = 6A	-	0.615	Ω

NOTES:

1. Pulse test, 300µs max.
2. Absolute value.
3. Insitu Gamma bias must be sampled for both V_{GS} = 10V, V_{DS} = 0V and V_{GS} = 0V, V_{DS} = 80% BV_{DSS}.

Typical Performance Curves Unless Otherwise Specified

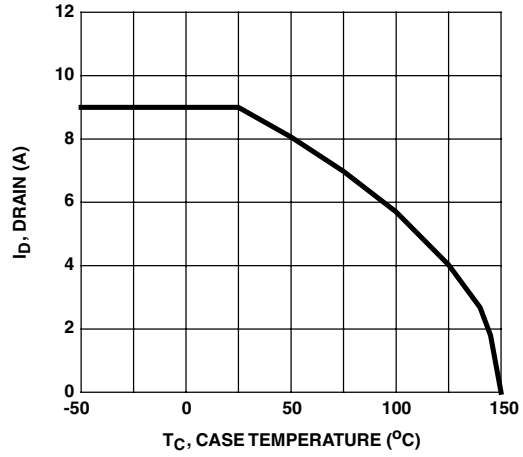


FIGURE 1. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

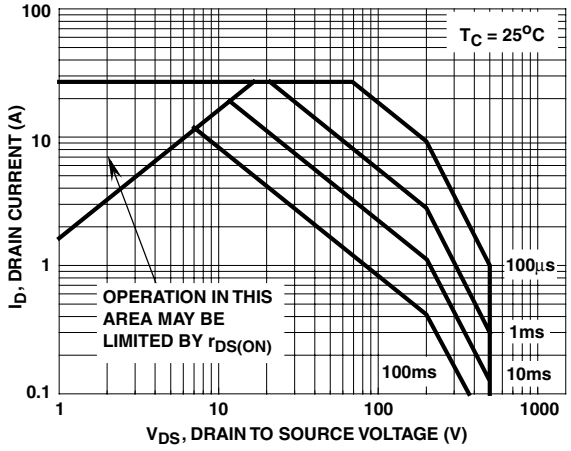


FIGURE 2. FORWARD BIAS SAFE OPERATING AREA

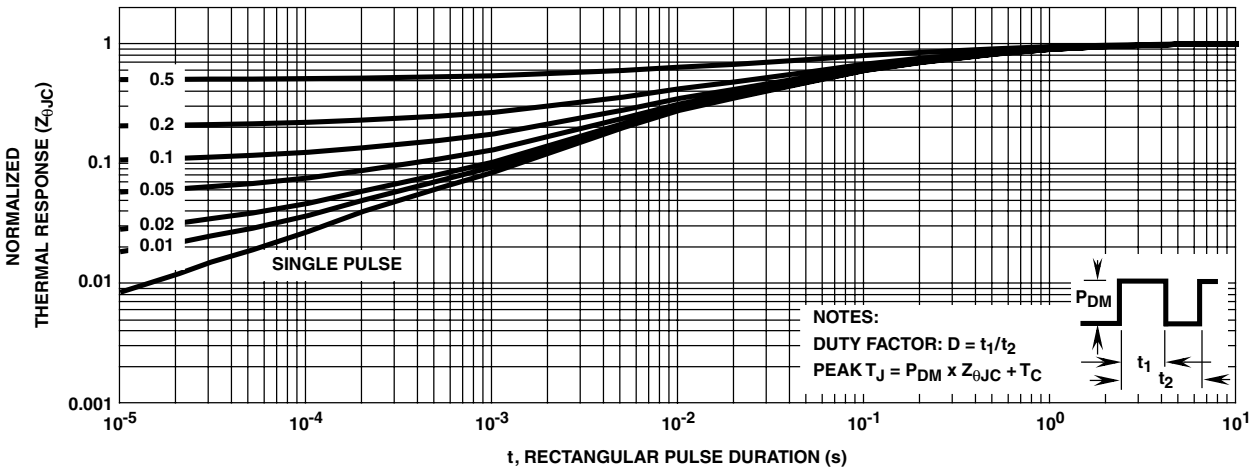


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL RESPONSE

Test Circuits and Waveforms

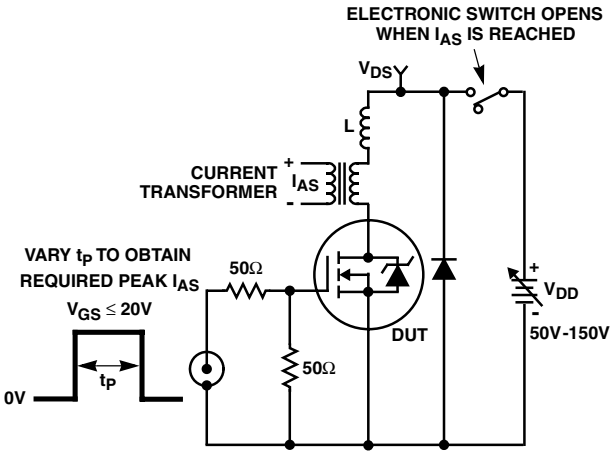


FIGURE 4. UNCLAMPED ENERGY TEST CIRCUIT

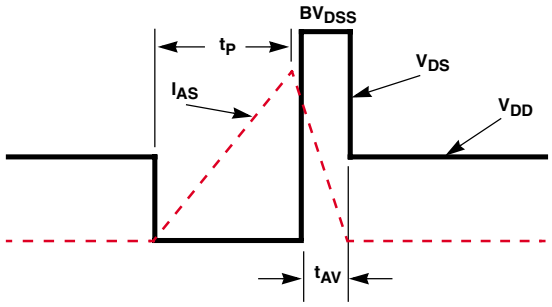


FIGURE 5. UNCLAMPED ENERGY WAVEFORMS

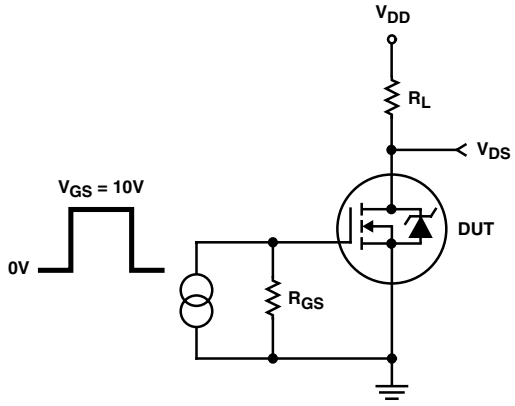


FIGURE 6. RESISTIVE SWITCHING TEST CIRCUIT

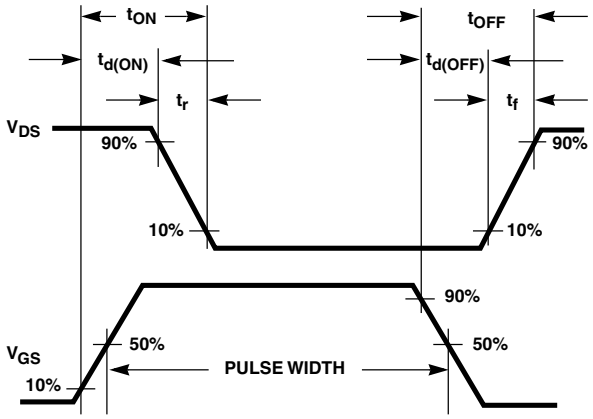
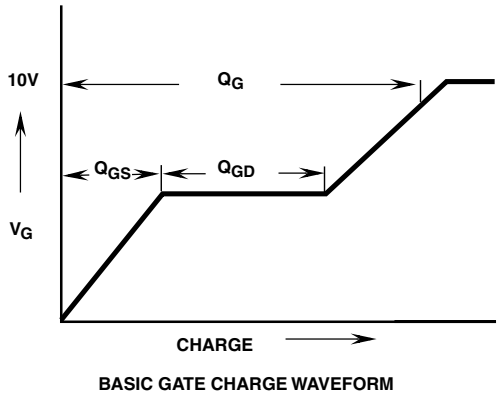


FIGURE 7. RESISTIVE SWITCHING WAVEFORMS



BASIC GATE CHARGE WAVEFORM

FIGURE 8. BASIC GATE CHARGE WAVEFORM

Screening Information

Screening is performed in accordance with the latest revision in effect of MIL-S-19500, (Screening Information Table).

Delta Tests and Limits (JANS) $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MAX	UNITS
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V$	±20 (Note 4)	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 80% Rated Value	±25 (Note 4)	μA
On Resistance	$r_{DS(ON)}$	$T_C = 125^oC$ at Rated I_D	±20% (Note 5)	Ω
Gate Threshold Voltage	$V_{GS(TH)}$	I_D = 1.0mA	±20% (Note 5)	V

NOTES:

4. Or 100% of Initial Reading (whichever is greater).
5. Of Initial Reading.

Screening Information

TEST	JANS
Gate Stress	V_{GS} = 30V, t = 250μs
Pind	Required
PDA	5%
Pre Burn-In Tests (Note 6)	MIL-S-19500 Group A, Subgroup 2 (All Static Tests at 25^oC)
Steady State Gate Bias (Gate Stress)	MIL-STD-750, Method 1042, Condition B V_{GS} = 80% of Rated Value, $T_A = 150^oC$, Time = 48 hours
Interim Electrical Tests (Note 6)	All Delta Parameters Listed in the Delta Tests and Limits Table
Steady State Reverse Bias (Drain Stress)	MIL-STD-750, Method 1042, Condition A V_{DS} = 80% of Rated Value, $T_A = 150^oC$, Time = 240 hours
Final Electrical Tests (Note 6)	MIL-S-19500, Group A, Subgroups 2 and 3

NOTE:

6. Test limits are identical pre and post burn-in.

Additional Screening Tests

PARAMETER	SYMBOL	TEST CONDITIONS	MAX	UNITS
Safe Operating Area	SOA	V_{DS} = 200V, t = 10ms	1.25	A
Unclamped Inductive Switching	I_{AS}	$V_{GS(PEAK)}$ = 15V, L = 0.1mH	27	A
Thermal Response	ΔV_{SD}	t_H = 100ms; V_H = 25V; I_H = 4A	136	mV
Thermal Impedance	ΔV_{SD}	t_H = 500ms; V_H = 25V; I_H = 4A	187	mV

Rad Hard Data Packages - Intersil Power Transistors

1. JANS Rad Hard - Standard Data Package

A. Certificate of Compliance

B. Serialization Records

C. Assembly Flow Chart

D. SEM Photos and Report

E. Preconditioning
- Attributes Data Sheet
- Hi-Rel Lot Traveler
- HTRB - Hi Temp Gate Stress Post Reverse Bias Data and Delta Data
- HTRB - Hi Temp Drain Stress Post Reverse Bias Delta Data

F. Group A
- Attributes Data Sheet

G. Group B
- Attributes Data Sheet

H. Group C
- Attributes Data Sheet

I. Group D
- Attributes Data Sheet

2. JANS Rad Hard - Optional Data Package

A. Certificate of Compliance

B. Serialization Records

C. Assembly Flow Chart

D. SEM Photos and Report

E. Preconditioning
- Attributes Data Sheet
- Hi-Rel Lot Traveler
- HTRB - Hi Temp Gate Stress Post Reverse Bias Data and Delta Data
- HTRB - Hi Temp Drain Stress Post Reverse Bias Delta Data
- X-Ray and X-Ray Report

F. Group A
- Attributes Data Sheet
- Hi-Rel Lot Traveler
- Subgroups A2, A3, A4, A5 and A7 Data

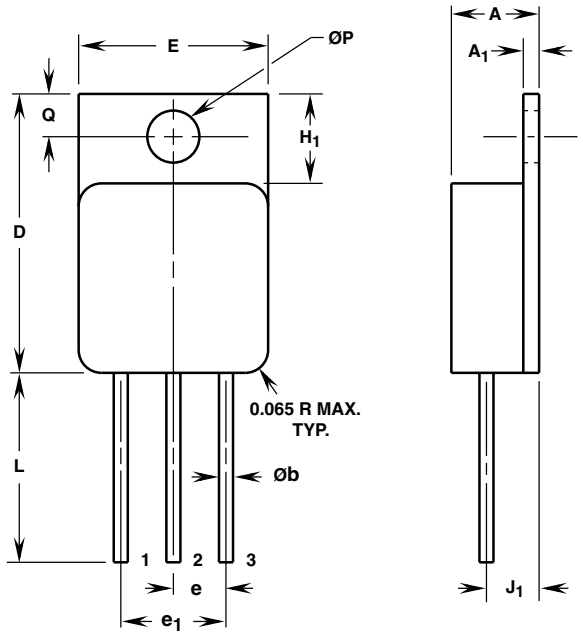
G. Group B
- Attributes Data Sheet
- Hi-Rel Lot Traveler
- Subgroups B1, B3, B4, B5 and B6 Data

H. Group C
- Attributes Data Sheet
- Hi-Rel Lot Traveler
- Subgroups C1, C2, C3 and C6 Data

I. Group D
- Attributes Data Sheet
- Hi-Rel Lot Traveler
- Pre and Post Radiation Data

TO-254AA

3 LEAD JEDEC TO-254AA HERMETIC METAL PACKAGE



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.249	0.260	6.33	6.60	-
A_1	0.040	0.050	1.02	1.27	-
Øb	0.035	0.045	0.89	1.14	2, 3
D	0.790	0.800	20.07	20.32	-
E	0.535	0.545	13.59	13.84	-
e	0.150 TYP		3.81 TYP		4
e_1	0.300 BSC		7.62 BSC		4
H_1	0.245	0.265	6.23	6.73	-
J_1	0.140	0.160	3.56	4.06	4
L	0.520	0.560	13.21	14.22	-
ØP	0.139	0.149	3.54	3.78	-
Q	0.110	0.130	2.80	3.30	-

NOTES:

1. These dimensions are within allowable dimensions of Rev. A of JEDEC outline TO-254AA dated 11-86.
2. Add typically 0.002 inches (0.05mm) for solder coating.
3. Lead dimension (without solder).
4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
5. Die to base BeO isolated, terminals to case ceramic isolated.
6. Controlling dimension: Inch.
7. Revision 1 dated 1-93.

WARNING!

BERYLLIA WARNING PER MIL-S-19500

Packages containing beryllium oxide (BeO) shall not be ground, machined, sandblasted, or subject to any mechanical operation which will produce dust containing any beryllium compound. Packages containing any beryllium compound shall not be subjected to any chemical process (etching, etc.) which will produce fumes containing beryllium or its' compounds.

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DOME™	ISOPLANAR™	QT Optoelectronics™	UHC™
EcoSPARK™	LittleFET™	Quiet Series™	UltraFET®
E^2CMOS^{TM}	MicroFET™	SILENT SWITCHER ®	VCX™
EnSigna™	MICROWIRE™	SMART START™	
FACT™	OPTOLOGIC™	Star* Power™	
FACT Quiet Series™	OPTOPLANAR™	Stealth™	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.